Special Issue

Security, Privacy and Reliability in Computer Communications

Message from the Guest Editor

Future communication networks promise to achieve ultra-fast data rates and minimal latency to perform complex tasks by integrating the capabilities of various heterogeneous networks and emerging technologies such as 5G/6G, artificial intelligence, edge intelligence, and software-defined networks. These technologies pose considerable difficulties in establishing safe and reliable networks to address numerous threats and privacy issues. New research technologies are essential to preserve privacy, prevent attacks, and achieve the necessary reliability. The aim of this Special Issue is to investigate the latest research trends and recent development of the security, privacy and reliability of computer communication and networks that are able to support reliable future communication networks.

Guest Editor

Dr. Jaehyuk Choi

School of Computing, Gachon University, 1342, Seongnam-daero, Sujeong-gu, Seongnam-si 13120, Republic of Korea

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

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